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Title:

JP11191322A2: TIN-DLATED WIRE FOR ELECTRONIC EQUIPMENT

Tin-plated wire for cable of electronic devices - containing tin-silver-

bismuth alloy [Derwent Record]

ਊ Country:

JP Japan

₽Kind:

PInventor:

ICHIKAWA TAKAO:

AOYAMA MASAYOSHI;

KONISHI KENJI:

HITACHI CABLE LTD

HITACHI SENZAI KK

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Published / Filed:

1999-07-13 / 1997-12-26

& Application

JP1997000358973

Number: § IPC Code:

H01B 5/02; C22C 13/02; C23C 2/08; C23C 2/38;

Priority Number:

1997-12-26 JP1997000358973

♀Abstract:

PROBLEM TO BE SOLVED: To provide a tin-plated wire for electronic equipment whose bending resistance (bending life) is improved without changing the material of the conductor (a material subjected to plating).

SOLUTION: A tin-silver-bismuth alloy containing 2.0-5.0 wt.% of silver (Ag) and 1.0-30 wt.% of bismuth(Bi) is used as a tin plating and consequently this tin-plated wire for electronic equipment has higher strength than a conventional wire plated with pure tin and a

prolonged bending life. This plated wire is of an assembling stranded wires preferably produced by plating tough pitch copper wires (a soft copper wire) with 0.08 mm wire diameter with a tinsilver- bismuth alloy in 0.5-1.0 µm thickness and stranding 60 of

wires plated in such a manner. COPYRIGHT: (C)1999,JPO

None

Other Abstract

CHEMABS 131(07)091147R CHEMABS 131(07)091147R DERABS

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